acid), polyacrylic acid, polyacrylamide, aminopolyacrylamide, ammonium polyacrylate, sodium polyacrylate, ammonium polyamidate, sodium polyamidate, polyglyoxylic acid, etc.; and vinyl polymers such as polyvinyl alcohol, polyvinylpyrrolidone, polyacrolein, etc.--

Please delete the paragraph at page 27, lines 14-20, and substitute therefor the following new paragraph:

--In a case where a protective film-forming agent is divided into three portions to be separately in three constituent elements, the metal-polishing liquid material may be composed of, for example, a first constituent element A that comprises an oxidizing agent and a part of the protective film-forming agent, a second constituent element B that comprises an oxidized-metal etchant and another part of the protective film-forming agent, and a third constituent element C that comprises the remaining part of the protective film-forming agent and a dissolution promoter.--

IN THE CLAIMS

Please amend the claims presently in the application as follows:

 $\mathcal{B}'/4$. (Amended) The metal-polishing liquid material according to claim 2, wherein the dissolution promoter is a surfactant.

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6. (Amended) The metal-polishing liquid material according to claim 2, wherein the dissolution promoter is a solvent in which the solubility of the protective film-forming agent is at least 25 g/liter.

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10. (Amended) The metal-polishing liquid material according to claim 2, wherein at least a part of the protective film-forming agent is solid having a mean particle size of at most 100 μm .

- 11. (Amended) The metal-polishing liquid material according to claim 2, further comprising abrasive grains.
- 17. (Amended) A method for producing a metal-polishing liquid, comprising a step of diluting the metal-polishing liquid material of claim 2 with a diluent.
- 20. (Amended) The method for producing a metal-polishing liquid according to claim 19, wherein the diluent is water or an aqueous diluent solution.

Please add the following new claims to the application:

- --27. The metal-polishing liquid material according to claim 1, wherein the dissolution promoter is a surfactant.
- 28. The metal-polishing liquid material according to claim 27, wherein the surfactant is at least one of esters,

ethers, polysaccharides, salts of amino acids, polycarboxylic acids, salts of polycarboxylic acids, vinyl polymers, sulfonic acids, sulfonates, and amides.

- The metal-polishing liquid material according to claim 1 wherein the dissolution promoter is a solvent in which the solubility of the protective film-forming agent is at least 25 g/liter.
- 30. The metal-polishing liquid material according to claim 29, wherein the solvent is a good solvent for the protective film-forming agent.
- 31. The metal-polishing liquid material according to claim 29, wherein the solvent is at least one of alcohols, ethers and ketones.
- 32. The metal polishing liquid material according to claim 29, wherein the amount of the solvent is smaller than 50 g relative to 100 g of a total amount of the material.
- 33. The metal-polishing liquid material according to claim 1, wherein at least a part of the protective film-forming agent is solid having a mean particle size of at most 100 μm .
- 34. The metal-polishing liquid material according to claim 1, further comprising abrasive grains.

35. A method for producing a metal-polishing liquid, comprising a step of diluting the metal-polishing liquid material of plaim 1 with a diluent.

36. The method for producing a metal-polishing liquid according to claim 17, wherein the diluent is water or an aqueous diluent solution.--